



Designing & Testing Lightweight Heatsink for SiC PV Converter

Team 13

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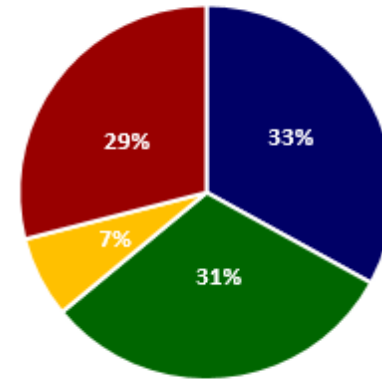
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Project Statement

- By decreasing the weight of the heatsink, the power density of the converter can be increased
- Provide a heatsink design & test method for power converters that will allow for optimal system performance

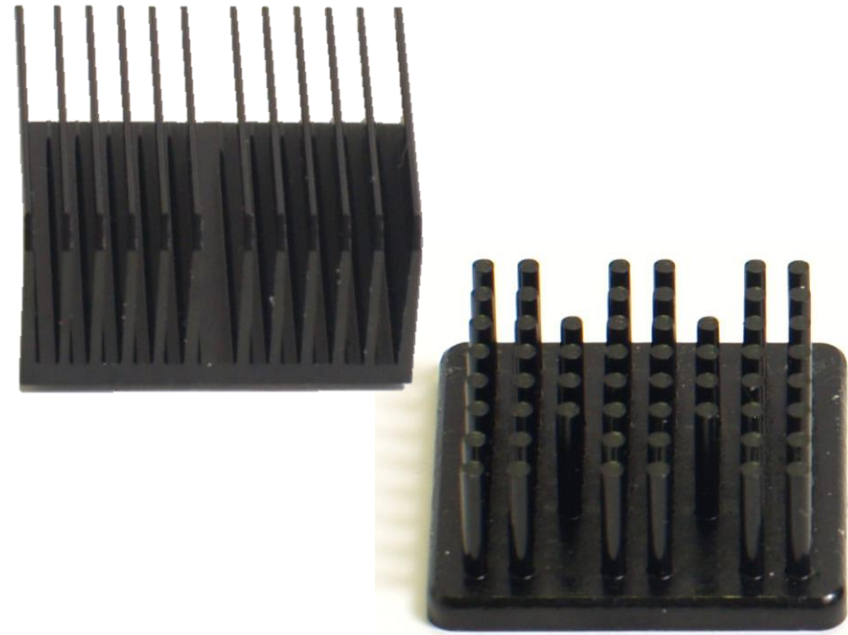
Weight Distribution for 100kW Power Converter



■ Heatsink ■ Magnetics ■ Modules ■ PCB & Components

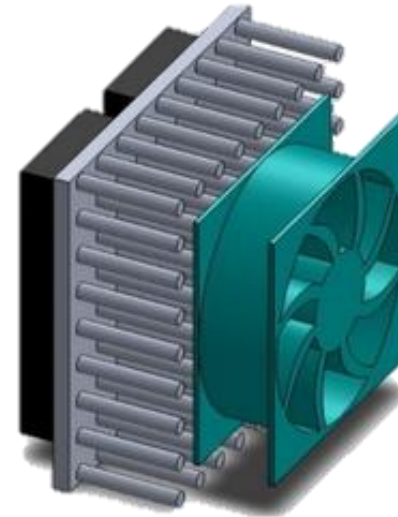
Project Scope

- Design an optimized thermal system for power converters to increase the power density
 - Plate fin vs. pin fin
- Implement a modular heatsink design to advance the current system



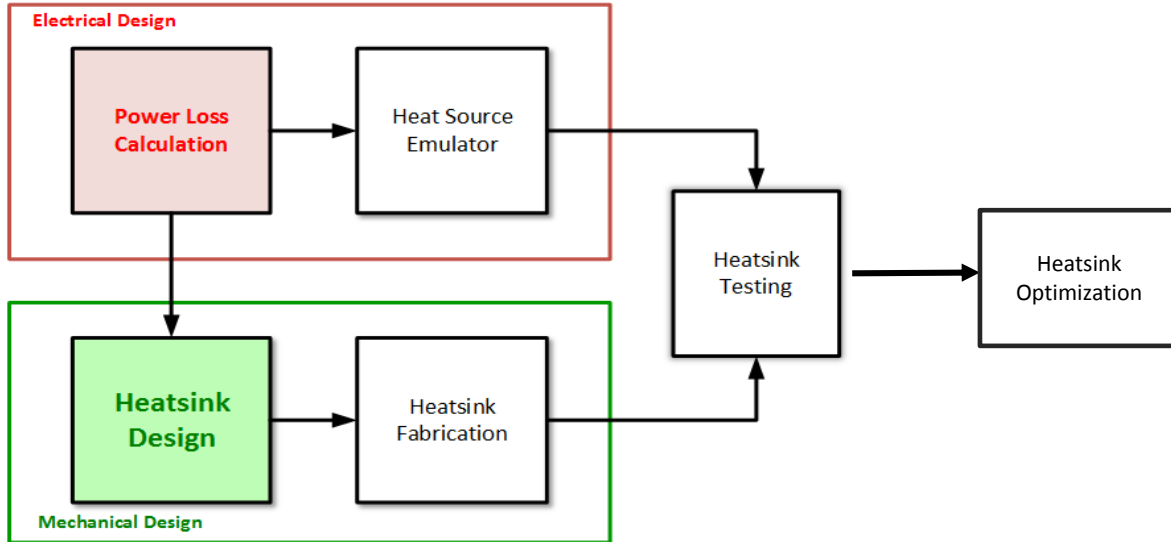
Project Objectives

- Increase the power density from 2.5 kW/kg
- Optimize design for pin fin heatsink
- Implement bi-modular design for a pin fin heatsink
- Select the appropriate fan size and speed



Plan & Methodology

- Through research & calculations, determine initial plate and pin fin modular heatsink designs
- Design & build heat source emulator for heatsink testing
- Verify calculations using both COMSOL simulations and experimental results
- Further improve design through optimized calculations



Heatsink Analysis

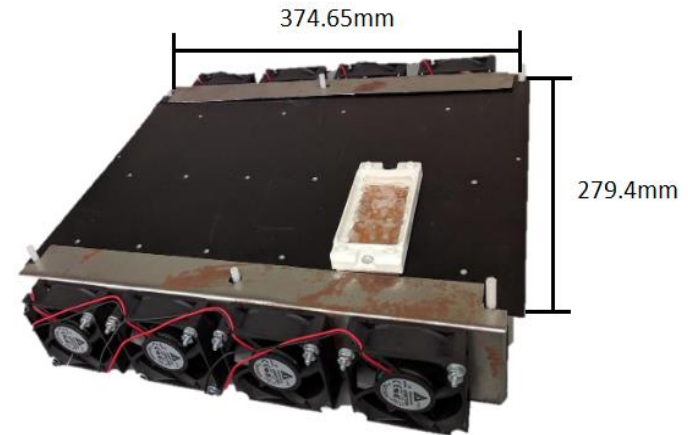
- Plate fin & Pin fin heatsink designs were analyzed using calculations and simulations assuming 120W heat source and an ambient temperature of 20°C

Heatsink Design	Plate Fin	Pin Fin
Size	127mm x 127mm x 69.2mm	113.7mm x 113.7mm x 17.8mm
Weight w/ fans	0.954 kg	0.553 kg
Fan Speed	1.73 m ³ /min (x2)	3.03 m ³ /min
Fan Orientation	Lateral	Axial
Junction Temperature	41°C	36°C

Weight Comparisons

- Original heatsink weighs 6.45 kg, supports 8 power modules

Heatsink Design	Plate Fin	Pin Fin
Weight (2 modules)	0.954 kg	0.553 kg
Weight (8 modules)	3.816 kg	2.212 kg
Weight Reduction %	40.8%	65.7%



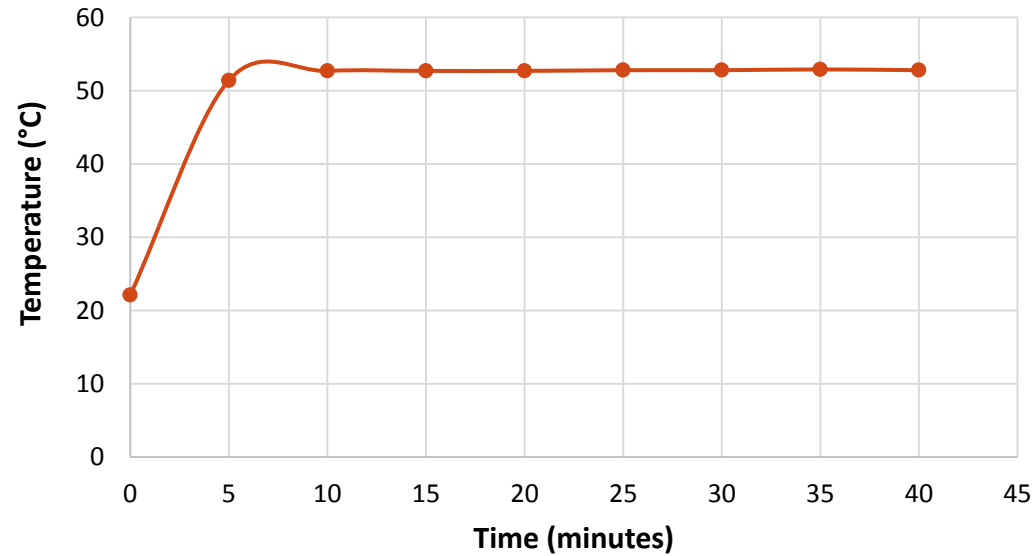
CAPS Original Heatsink

Preliminary Results: Plate Fin

- Plate fin tested using heat source emulators until steady state temperature was reached
- Fan power supply: 0.5A, 5.27V
- Power module power supply: 2.5A, 24.5V
- Junction Temperature = 52.8°C
- Thermal Resistance ≈ 0.257 K/W

$$R = \frac{T_{max} - T_{room}}{\dot{Q}}$$

Heatsink Testing, Temperature vs. Time



PowerAmerica Conference

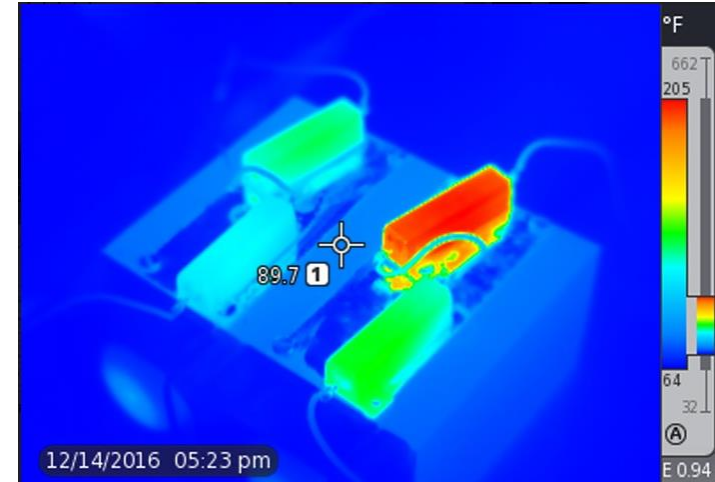


- Attended PowerAmerica Annual Meeting at North Carolina State University
- Presented project results to industry professionals & academic researchers
- Gained further incite into significance of thermal management for SiC PV converters

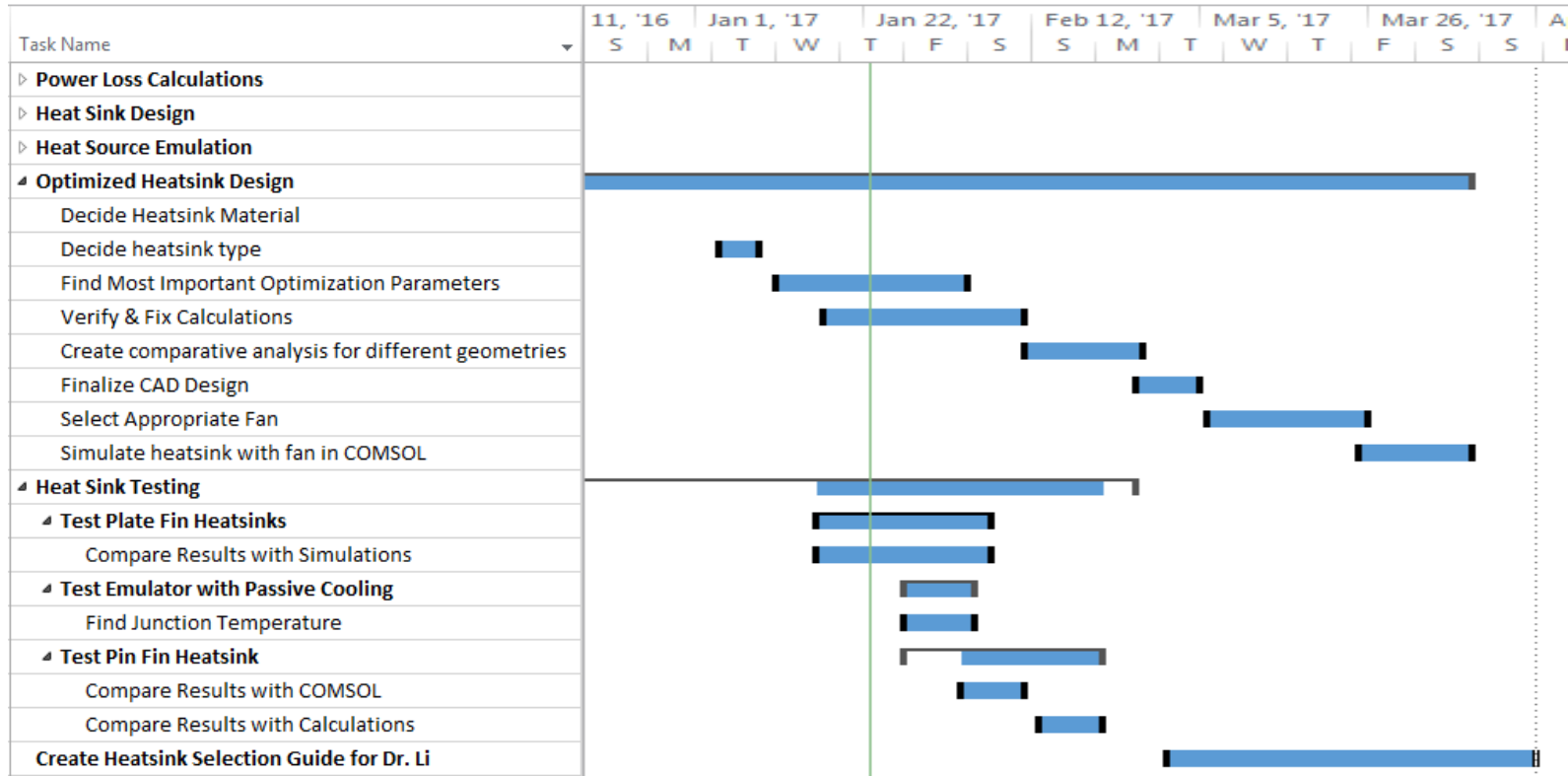


Challenges

- Improvements have been made in COMSOL
- Testing:
 - One resistor had inconsistent thermal results
 - Power output of resistors in theory: 200 Watts
 - Power output of resistors in experiment: 120 Watts
 - Fan was not at max speed during first stage of testing
- Calculations: Significant error exists in the pin fin calculations
 - Current identified sources include
 1. Nusselt Number Equations
 2. Average Velocity of the air through the fins



Gantt Chart



Summary

Provide a heatsink design & test method for power converters that will allow for optimal system performance. By decreasing the weight of the heatsink we can increase the power density of the converter.

- Continue testing to eliminate errors and perform comparison between simulations and test results
- Eliminate error generated from the pin fin calculations
- Optimize the Pin Fin Heatsink design
- Provide Dr. Li with a Heatsink Selection Guide